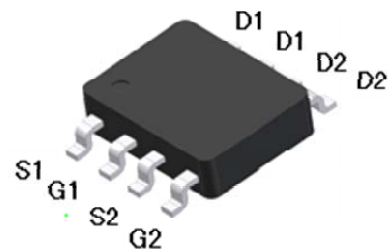
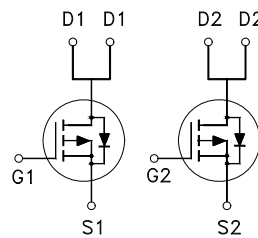


Dual P-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	-30V
R _{DS(on)} (MAX.)	24mΩ
I _D	-8A



UIS, R_g 100% Tested

Pb-Free Lead Plating



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V _{GS}	±25	V
Continuous Drain Current	T _C = 25 °C	I _D	-8	A
	T _C = 100 °C		-6	
Pulsed Drain Current ¹		I _{DM}	-32	
Avalanche Current		I _{AS}	-12	
Avalanche Energy	L = 0.1mH, I _D = -8A, R _G = 25Ω	E _{AS}	3.2	mJ
Repetitive Avalanche Energy ²	L = 0.05mH	E _{AR}	1.6	
Power Dissipation	T _A = 25 °C	P _D	2	W
	T _A = 100 °C		1.1	
Operating Junction & Storage Temperature Range		T _J , T _{stg}	-55 to 150	°C

100% UIS testing in condition of V_D = -15V, L = 0.1mH, V_G = -10V, I_L = -8A, Rated V_{DSS} = -30V P-CH

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R _{θJC}		25	°C / W
Junction-to-Ambient ³	R _{θJA}		62.5	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

³62.5°C / W when mounted on a 1 in² pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1	-1.5	-3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
		$V_{DS} = 0V, V_{GS} = \pm 25V$			± 500	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -24V, V_{GS} = 0V$			-1	μA
		$V_{DS} = -20V, V_{GS} = 0V, T_J = 125\text{ }^{\circ}C$			-10	
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = -5V, V_{GS} = -10V$	-8			A
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = -10V, I_D = -8A$		20.5	24	m Ω
		$V_{GS} = -4.5V, I_D = -6A$		29	37	
Forward Transconductance ¹	g_{fs}	$V_{DS} = -5V, I_D = -8A$		24		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -15V, f = 1MHz$		1407		pF
Output Capacitance	C_{oss}			208		
Reverse Transfer Capacitance	C_{rss}			164		
Gate Resistance	R_g	$V_{GS} = 15mV, V_{DS} = 0V, f = 1MHz$		4.5		Ω
Total Gate Charge ^{1,2}	$Q_g(V_{GS}=10V)$	$V_{DS} = -15V, V_{GS} = -10V,$ $I_D = -8A$		20.3		nC
	$Q_g(V_{GS}=4.5V)$			9.8		
Gate-Source Charge ^{1,2}	Q_{gs}			3.2		
Gate-Drain Charge ^{1,2}	Q_{gd}			4.9		
Turn-On Delay Time ^{1,2}	$t_{d(on)}$	$V_{DS} = -15V,$ $I_D = -1A, V_{GS} = -10V, R_{GS} = 2.7\Omega$		10		nS
Rise Time ^{1,2}	t_r			8		
Turn-Off Delay Time ^{1,2}	$t_{d(off)}$			25		
Fall Time ^{1,2}	t_f			6		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T _C = 25 °C)						
Continuous Current	I_S				-2.3	A
Pulsed Current ³	I_{SM}				-9.2	
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{GS} = 0V$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_F = I_S, dI_F/dt = 100A / \mu S$		32		nS
Reverse Recovery Charge	Q_{rr}			26		nC

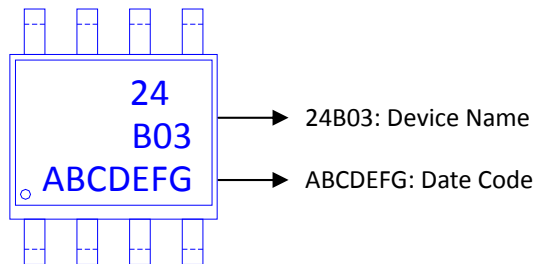
¹Pulse test : Pulse Width $\leq 300\mu$ sec, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

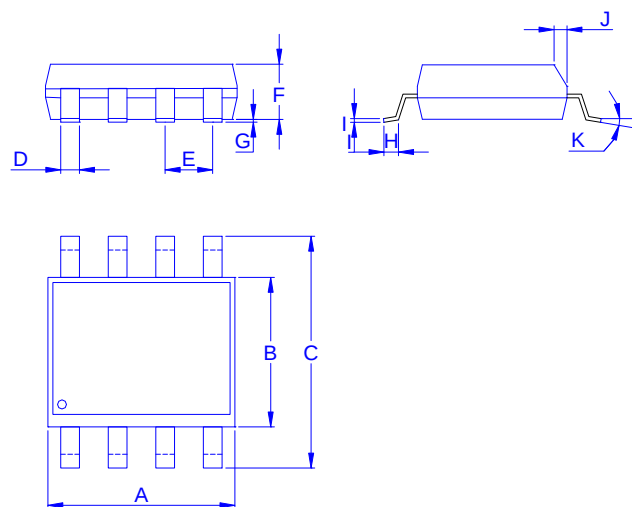
³Pulse width limited by maximum junction

temperature. **Ordering & Marking Information:**

Device Name: LB24B03HD for SOP-8



Outline Drawing



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K
in.	4.70	3.70	5.80	0.33		1.20	0.08	0.40	0.19	0.25	0°
Typ.					1.27						
Max.	5.10	4.10	6.20	0.51		1.62	0.28	0.83	0.26	0.50	8°

